

austriamicrosystems introduces advanced Through Silicon Via technology for 3D sensor integration

Reliable sensor and CMOS IC integration concept enables smallest form factors

Unterpremstaetten, Austria (May 27, 2009) – austriamicrosystems business unit Full Service Foundry today announced the availability of its patented Through Silicon Via (TSV) technology for foundry customers. With the TSV technology two eight inch wafers can be electrically connected. With typical TSV depths of 200µm to 300µm, it is especially targeting 3D integration of CMOS ICs and sensor components. Due to a flexible manufacturing concept customer specific modifications as well as varying wafer thicknesses can be supported. The patented TSV manufacturing technology is electrically proven and available for production.

The TSV technology addresses a variety of markets demanding 3D integration of CMOS ICs, photo sensors, gas sensors, power devices or MEMS components such as automotive, industrial & consumer applications. Foundry customers using the austriamicrosystems TSV concept immediately benefit from a significantly reduced form factor, systems cost reduction as well as performance improvements due to shortened interconnect lengths. A proprietary back side re-distribution layer concept enables various front and back side IO pad connections and provides customers with utmost flexibility in IC and sensor arrangement.

"This new 3D integration technology further extends our portfolio of industry-leading Mixed Signal Analog and High Voltage technologies and provides customer-specific solutions for sensor integration. The innovative TSV technology can be combined in a fully flexible manner with any of our 0.35µm analog specialty technologies such as CMOS, HV-CMOS, SiGe BiCMOS or embedded Non-Volatile Memory. By providing our customers with early manufacturing access to this new technology we can support them in realizing differentiated systems solutions," states Thomas Riener, General Manager Business Unit Full Service Foundry at austriamicrosystems.

"We see our role in providing designers with competitive advantages from technology which further enhances the competitiveness of their products," comments Martin Schrems, Director of Process Development & Implementation at austriamicrosystems. "In analogy to our leading High-Voltage CMOS technology we have focused our TSV developments on creating a highly scalable, very low complexity and cost-effective technology platform. Beyond that TSV is a synergetic extension to our High-Voltage CMOS technology portfolio."

About austriamicrosystems

austriamicrosystems' business unit Full Service Foundry has successfully positioned itself in the analog/mixed-signal foundry market offering well-established RF CMOS, High-Voltage CMOS, BiCMOS and SiGe-BiCMOS processes. With superior support during the design phase, high-end tools and experienced engineers, austriamicrosystems succeeds to be an attractive analog foundry partner especially for fabless design houses.

austriamicrosystems is a leading designer and manufacturer of high performance analog ICs, combining more than 27 years of analog design capabilities and system know-how with its own state-of-the-art manufacturing and test facilities. austriamicrosystems leverages its expertise in low power and high accuracy to provide industry-leading customized and standard analog products. Operating worldwide with more than 1,000 employees, austriamicrosystems focuses on the

areas of power management, sensors & sensor interfaces, and mobile infotainment in its markets Communications, Industry & Medical and Automotive, complemented by its Full Service Foundry activities. austriamicrosystems is listed on the SIX Swiss Exchange in Zurich (ticker: AMS). For more information, please visit www.austriamicrosystems.com.

For further information

Press Contact

austriamicrosystems AG
Ulrike Anderwald
Marketing Communications Manager
Tel: +43 (0) 3136 500 5856
Fax: +43 (0) 3136 500 5420
press@austriamicrosystems.com
www.austriamicrosystems.com

Technical Contact

austriamicrosystems AG
Andreas Wild
Product Marketing Manager Full Service Foundry
Tel: +43 (0) 3136 500 4400
Fax: +43 (0) 3136 500 5420
andreas.wild@austriamicrosystems.com
www.austriamicrosystems.com